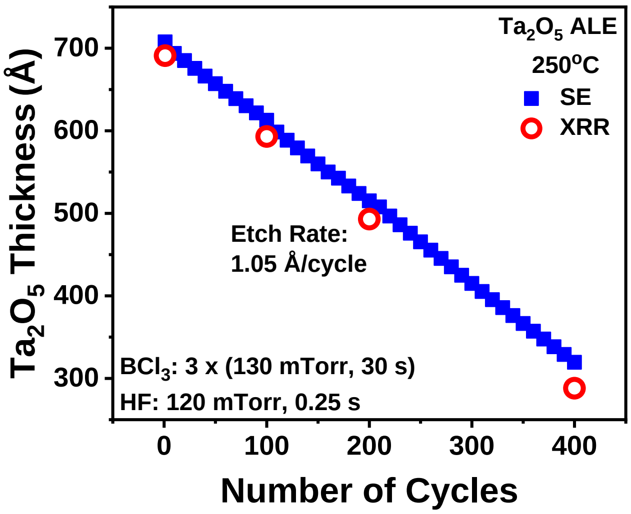

Figure 1.

Ta_2O_5 thickness versus number of Ta_2O_5 ALE cycles using BCl_3 and HF as the reactants at 250°C. Etch rate is 1.05 Å/cycle.

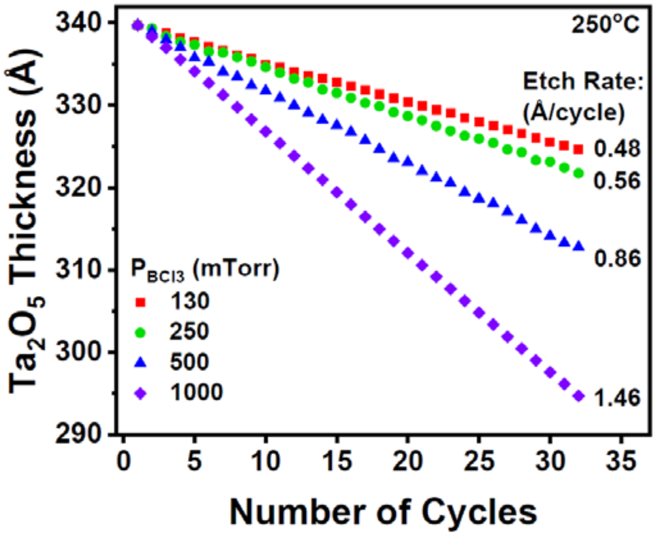

Figure 2.

Ta_2O_5 thickness versus number of Ta_2O_5 ALE cycles using different BCl_3 pressures at 250°C. Etch rate increases with pressure from 0.48 Å/cycle at 130 mTorr to 1.46 Å/cycle at 1000 mTorr.

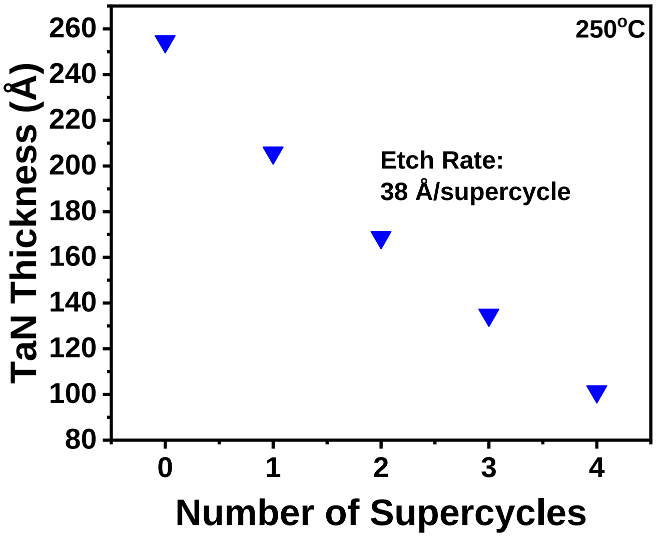

Figure 3.

TaN thickness versus number of supercycles using an initial O_3 exposure and then 60 Ta_2O_5 ALE cycles with BCl_3 and HF as the reactants at 250°C. Etch rate is 38 Å/supercycle.